

## **TIDA-10613 REV E1 Bill of Materials**

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
!PCB1	1		TIDA-10613	Any	Printed Circuit Board	
C1, C6	2	0.1uF	GRM155R71C104KA88D	MuRata	CAP, CERM, 0.1 uF, 16 V, +/- 10%, X7R, 0402	0402
C2	1	100pF	GRM1885C2A101JA01D	MuRata	CAP, CERM, 100pF, 100V, +/-5%, C0G/NP0, 0603	0603
C3	1	68uF	16TQC68MYF	Panasonic	CAP, TA, 68uF, 16V, +/-20%, 0.05 ohm, SMD	7.3x2.0x4.3mm
C4	1	47uF	GRM32ER61C476ME15L	MuRata	CAP, CERM, 47uF, 16V, +/-20%, X5R, 1210	1210
C5	1	330uF	EEF-GX0D331R	Panasonic	CAP, TA, 330uF, 2 V, +/- 20%, 0.003 ohm, SMD	SMD_7.3x1.9x4.3mm
C7	1	22uF	GRM31CR71A226KE15L	MuRata	CAP, CERM, 22uF, 10 V, +/- 10%, X7R, 1206	1206
C8	1	0.1uF	GRM188R61E104KA01D	MuRata	CAP, CERM, 0.1uF, 25V, +/-10%, X5R, 0603	0603
C9	1	10uF	GRM21BR61E106MA73	MuRata	CAP, CERM, 10uF, 25V, +/-20%, X5R, 0805	0805
C10	1	22uF	GRM21BR60J226ME39L	MuRata	CAP, CERM, 22uF, 6.3V, +/-20%, X5R, 0805	0805
C11	1	3300pF	GRM155R71H332KA01D	MuRata	CAP, CERM, 3300pF, 50V, +/-10%, X7R, 0402	0402
C12	1	220uF	EEFSX0G221ER	Panasonic	CAP, AL, 220uF, 4V, +/-20%, 9 ohm, SMD	7.3x1.8x4.3mm
C13, C14, C15,	4	47uF	GRM32ER60J476ME20L	MuRata	CAP, CERM, 47uF, 6.3V, +/-20%, X5R, 1210	1210
C16						
C17, C18, C19,	4	0.1uF	GRM155R61E104KA87D	MuRata	CAP, CERM, 0.1µF, 25 V, +/- 10%, X5R, 0402	0402
C36						
C20	1	1uF	GRM188R61E105KA12D	MuRata	CAP, CERM, 1uF, 25V, +/-10%, X5R, 0603	0603
C21, C22	2	22uF	EEE-FC1C220R	Panasonic	CAP, AL, 22uF, 16V, +/-20%, 1.8 ohm, SMD	SMT Radial C
C23, C29	2	10uF	GRM188R60J106ME47D	MuRata	CAP, CERM, 10uF, 6.3 V, +/- 20%, X5R, 0603	0603
C24, C25, C26, C27	4	47uF	GRM32ER61C476KE15L	MuRata	CAP, CERM, 47uF, 16V, +/-10%, X5R, 1210	1210
C28	1	470uF	EEF-GX0E471L	Panasonic	CAP, TA, 470uF, 2.5 V, +/- 20%, 0.003 ohm, SMD	SMD_7.3x1.9x4.3mm
C30, C31, C32,	5	100uF	GRM32ER60J107ME20L	MuRata	CAP, CERM, 100uF, 6.3V, +/-20%, X5R, 1210	1210
C33, C34						
C35, C37	2	10uF	GRM21BR61A106KE19L	MuRata	CAP, CERM, 10 μF, 10 V, +/- 10%, X5R, 0805	0805
C38, C39	2	10uF	GRM21BR61E106MA73	MuRata	CAP, CERM, 10 μF, 25 V, +/- 20%, X5R, 0805	0805
C40	1	0.033uF	C0805C333K5RACTU	Kemet	CAP, CERM, 0.033 μF, 50 V, +/- 10%, X7R, 0805	0805
C41	1	100pF	GRM1535C1H101JDD5D	MuRata	CAP, CERM, 100 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402
D1	1	5.1V	BZT52C5V1T-7	Diodes Inc.	Diode, Zener, 5.1V, 300mW, SOD-523	SOD-523
H1, H2, H3, H4	4		SJ-5303 (CLEAR)	3M	Bumpon, Hemisphere, 0.44 X 0.20, Clear	Transparent Bumpon
J1	1		ED120/2DS	On-Shore Technology	TERMINAL BLOCK 5.08MM VERT 2POS, TH	TERM_BLK, 2pos, 5.08mm
J2	1		PEC02SAAN	Sullins Connector Solutions	Header, 100mil, 2x1, Tin, TH	Header, 2 PIN, 100mil. Tin
J3, J4, J5, J6	4		6095	Keystone	Standard Banana Jack, Uninsulated	Keystone_6095
L1	1	10uH	XAL4040-103MEB	Coilcraft	Inductor, Shielded, Composite, 10uH, 3A, 0.084 ohm, SMD	4.0x4.1x4.0mm
LBL1	1		THT-14-423-10	Brady	Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	PCB Label 0.650"H x 0.200"W
R1	1	68.1k	CRCW060368K1FKEA	Vishay-Dale	RES, 68.1k ohm, 1%, 0.1W, 0603	0603
R2	1	49.9	CRCW060349R9FKEA	Vishay-Dale	RES, 49.9 ohm, 1%, 0.1W, 0603	0603
R3	1	12.1k	CRCW060312K1FKEA	Vishay-Dale	RES, 12.1k ohm, 1%, 0.1W, 0603	0603
R4	1	1.13k	CRCW06031K13FKEA	Vishay-Dale	RES, 1.13 k, 1%, 0.1 W, 0603	0603
R5	1	105k	RT0603BRD07105KL	Yageo America	RES, 105k ohm, 0.1%, 0.1W, 0603	0603
R6	1	22.1k	CRCW060322K1FKEA	Vishay-Dale	RES, 22.1 k, 1%, 0.1 W, 0603	0603
R7	1	324k	CRCW0603324KFKEA	Vishay-Dale	RES, 324 k, 1%, 0.1 W, 0603	0603
R8, R9, R10, R13,	5	100k	CRCW0603100KJNEA	Vishay-Dale	RES, 100k ohm, 5%, 0.1W, 0603	0603
R16 R11	1	21.5k	CRCW040221K5FKED	Vishay-Dale	RES, 21.5 k, 1%, 0.063 W, 0402	0402
R12	1	178k	CRCW040221RSFRED	Vishay-Dale Vishay-Dale	RES, 178 k, 1%, 0.063 W, 0402	0402

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R14	1	10.0	CRCW060310R0FKEA	Vishay-Dale	RES, 10.0 ohm, 1%, 0.1W, 0603	0603
R15	1	1.50Meg	CRCW04021M50FKED	Vishay-Dale	RES, 1.50 M, 1%, 0.063 W, 0402	0402
R17	1	0	CRCW06030000Z0EA	Vishay-Dale	RES, 0 ohm, 5%, 0.1W, 0603	0603
R18	1	2.18k	RT0603DRE072K18L	Yageo America	RES, 2.18 k, 0.5%, 0.1 W, 0603	0603
SH-J1	1	1x2	969102-0000-DA	3M	Shunt, 100mil, Gold plated, Black	Shunt
TP1	1	White	5002	Keystone	Test Point, Miniature, White, TH	White Miniature Testpoint
TP2, TP4, TP6, TP8, TP9, TP10, TP14, TP16	8	Red	5010	Keystone	Test Point, Multipurpose, Red, TH	Red Multipurpose Testpoint
TP3, TP5, TP7, TP11, TP12, TP13, TP15, TP17		Black	5011	Keystone	Test Point, Multipurpose, Black, TH	Black Multipurpose Testpoint
U1	1		LP2998QMR/NOPB	Texas Instruments	DDR-I and DDR-II Termination Regulator, 8-pin PSOP, Pb-Free	MRA08A
U2	1		TPS560200DBV	Texas Instruments	4.5V to 18V Input, 500mA Synchronous Step Down SWIFT Converter, DBV0005A	DBV0005A
U3	1		LMZ31503RUQ	Texas Instruments	3A SIMPLE SWITCHER Power Module with 4.5V-14.5V Input in QFN Package, RUQ0047A	RUQ0047A
U4	1		LM3880QMFE-1AA/NOPB	Texas Instruments	Power Sequencer, 6-pin SOT-23, Pb-Free	MF06A
U5	1		TPS73101DBV	Texas Instruments	Cap-Free, NMOS, 150mA Low Dropout Regulator with Reverse Current Protection, DBV0005A	DBV0005A
U6	1		LMZ31520RLG	Texas Instruments	20A SIMPLE SWITCHER(R) Power Module with 3.0V-14.5V Input, RLG0072A	RLG0072A
U7	1		TPS7A3501DRV	Texas Instruments	Low Noise, High PSRR 1A Active Filter, DRV0006A	DRV0006A
U8	1		LP3892EMR-1.2/NOPB	Texas Instruments	1.5A Fast-Response Ultra Low Dropout Linear Regulators, 8-pin PSOP, Pb-Free	MRA08A
U9	1		LP3981ILD-2.5/NOPB	Texas Instruments	Micropower, 300mA Ultra Low-Dropout CMOS Voltage Regulator, 6-pin LLP, Pb-Free	LDC06D
FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial

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